



Epoxy for Potting

Product Description

JA723-52 is two component epoxy for electronic devices. This resin exhibits excellent toughness, low thermal stress and thermal shock resistance. It is easy to operate and suitable for electronic devices potting. A clean surface can be applied, the precise ratio while mixing Part A and Part B, and complete mixing of these two components are required to obtain optimum properties.

Features

1. After mixing, this resin is easy to operate and has excellent fluidity. It is used for potting.
2. Cured product has good surface gloss, excellent chemical resistance and solvent resistance.
3. This resin exhibits excellent toughness, low thermal stress and thermal shock resistance.
4. This product has no volatile materials and will not release any toxic volatilizations.
5. This product complies to the 2011/65/EU RoHS regulations.
6. This product obeys UL94V-0 regulations.
7. This product complies to chlorine < 900ppm, bromine < 900ppm, chlorine + bromine < 1500ppm.

Typical Uncured Properties

	JA723-52A	JA723-52B
Appearance	Liquid	Liquid
Color	Black	Colorless
Viscosity 25°C, cps	12,000~24,000	<200
	S14 20rpm	S21 100rpm
Specific Gravity	1.54	0.96

Typical Curing Properties*

Mix Ratio (A : B) by Weight	5 : 1
Pot Life, 25°C, hr	3
Tack Free Time, 25°C, hr	12
Through Cure Time, 25°C, day	5-7
Through Cure Time, 80°C, hr	1

*A : B = 5g : 1g

Direction of Use

1. Weight the correct proportions to within 2% accuracy and mix thoroughly together, scraping both the bottom and the sides of mixing container, until a homogeneous mixture is obtained.
2. Mix thoroughly by weight 5 : 1. Mix approximately 15 seconds after uniform color is obtained.
3. Bonding surfaces should be clean, dry and properly prepared.
4. For optimum properties mixed, this product should be used before its pot life.
5. Cure time on the really part will depend upon factors such as part geometry, materials to be bonded, bondline thickness and efficiency of the oven. Cure schedule should be confirmed with actual production parts and equipment.

Typical Cured Properties*1

Glass Transition Temp., (MDSC), °C	52
CTE*2 (<Tg), µm/m/°C	53
CTE*2 (>Tg), µm/m/°C	177
Durometer Hardness, Shore D	78
Specific Gravity	1.40
Degradation Temp, (TGA 10°C/min), °C	292
Weight Loss Ratio @100°C, %	0
Weight Loss Ratio @150°C, %	0.33
Weight Loss Ratio @200°C, %	0.84
Weight Loss Ratio @250°C, %	2.21
Weight Loss Ratio @300°C, %	6.00
Weight Loss Ratio @350°C, %	16.39
Volume Shrinkage, %	5.1
Dielectric Constant, 100Hz	4.1

*1 Specimen Cure Condition : 80°C/ 1hr

*2 CTE: Coefficient of Thermal Expansion

Storage and Shelf Life

The container should be stored in cool and dark place. The resin and hardener will become yellow under the sunlight. Replace the lid immediately after use. Keep without any possibility of wet when not using. Shelf life of this product is one year when stored below 14~34°C in original, unopened containers.

Caution

Some findings indicate a lack of potential for carcinogenicity with the compositions of this product by long term recurrent application to the skin. However, contact with skin is likely to produce mild transient reddening. It is important to remove adhesive from skin with soap and water thoroughly. DO NOT use solvents for cleaning hands. This product is of moderate acute toxicity by swallowing. If swallowed, call a physician. Avoid contact with eyes. In case of contact, flush with water for at least 15 minutes and get medical attention immediately. For specific information on this product, consult the Safety Data Sheet.